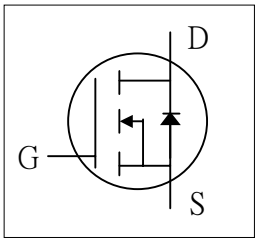
RoHS-compliant Product

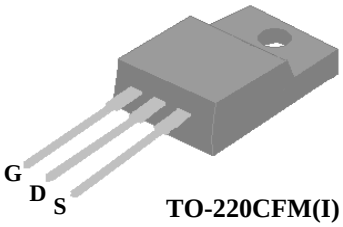
Advanced Power Electronics Corp.

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

- ▼ **100% Avalanche Test**
- ▼ **Fast Switching**
- ▼ **Simple Drive Requirement**
- ▼ **RoHS Compliant**



BV_{DSS}	600V
$R_{DS(ON)}$	3.6Ω
I_D	3.3A



TO-220CFM(I)

Description

AP03N70 series are specially designed as main switching devices for universal 90~265VAC off-line AC/DC converter applications. It provide high blocking voltage to overcome voltage surge and sag in the toughest power system with the best combination of fast switching design and cost-effectiveness.

The TO-220CFM package is widely preferred for all commercial-industrial through hole applications. The mold compound provides a high isolation voltage capability and low thermal resistance between the tab and the external heat-sink.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	±30	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V	3.3	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V	2.1	A
I_{DM}	Pulsed Drain Current[1]	10	A
P_D@T_C=25℃	Total Power Dissipation	29	W
E_{AS}	Single Pulse Avalanche Energy[2]	67	mJ
I_{AR}	Avalanche Current	3	A
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	4.3	℃/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	65	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	600	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[3]	V_{GS}=10V, I_D=1.6A	-	-	3.6	Ω
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	2	-	4	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=1.6A	-	2	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=600V, V_{GS}=0V	-	-	10	uA
	Drain-Source Leakage Current (T_j=125°C)	V_{DS}=480V, V_{GS}=0V	-	-	500	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±30V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge[3]	I_D=3A	-	12	20	nC
Q_{gs}	Gate-Source Charge	V_{DS}=480V	-	3	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=10V	-	5	-	nC
$t_{d(on)}$	Turn-on Delay Time[3]	V_{DD}=300V	-	9	-	ns
t_r	Rise Time	I_D=3A	-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=10Ω	-	18	-	ns
t_f	Fall Time	V_{GS}=10V	-	6	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	600	960	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	45	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	4	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[3]	I_S=3A, V_{GS}=0V	-	-	1.5	V
t_{rr}	Reverse Recovery Time[3]	I_S=3A, V_{GS}=0V,	-	422	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	2580	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Starting T_j=25°C , V_{DD}=50V , L=15mH , R_G=25Ω , I_{AS}=3A.

3.Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

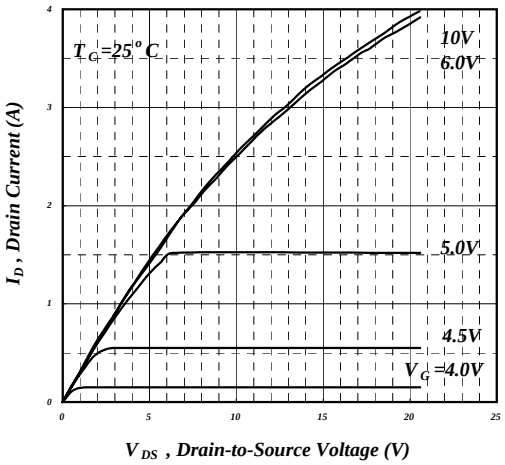


Fig 1. Typical Output Characteristics

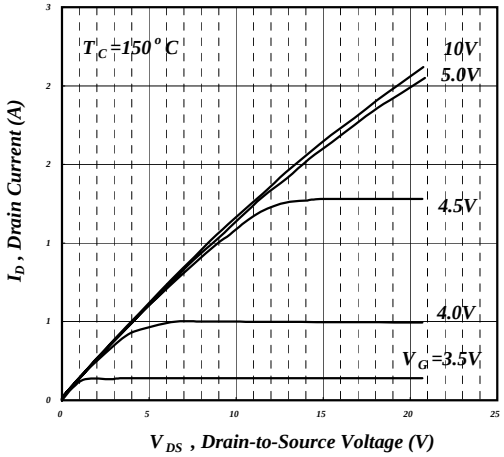


Fig 2. Typical Output Characteristics

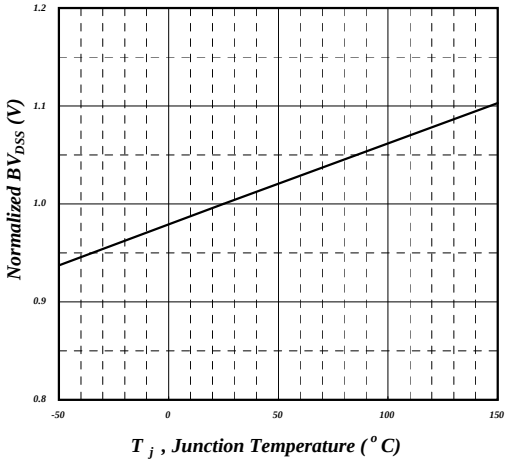


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

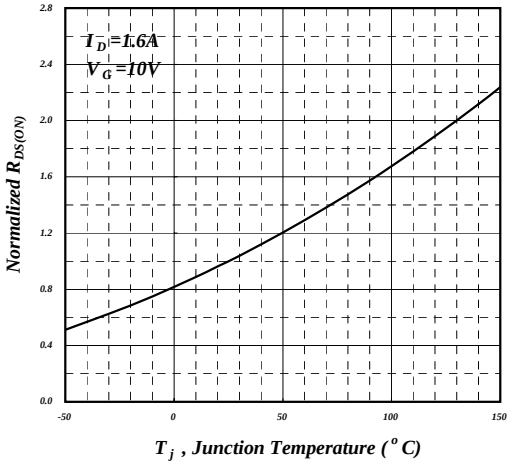


Fig 4. Normalized On-Resistance v.s. Junction Temperature

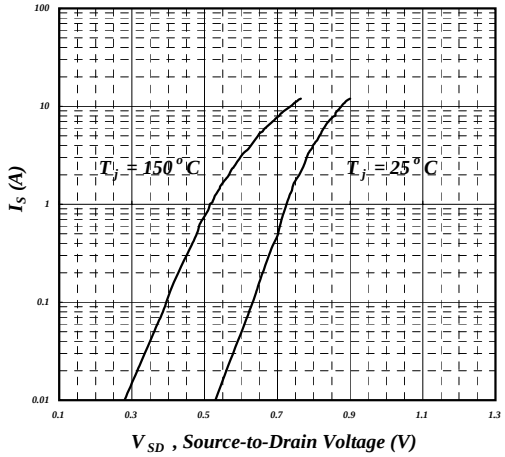


Fig 5. Forward Characteristic of Reverse Diode

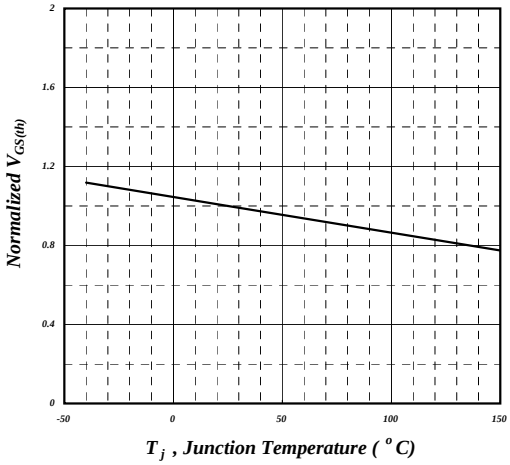


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

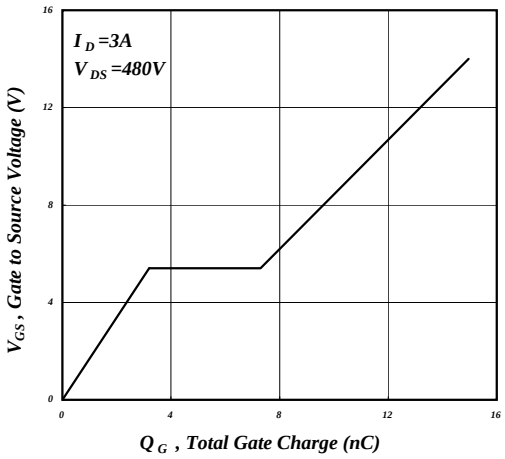


Fig 7. Gate Charge Characteristics

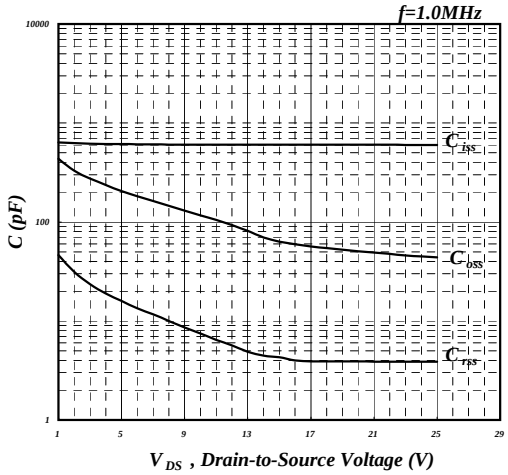


Fig 8. Typical Capacitance Characteristics

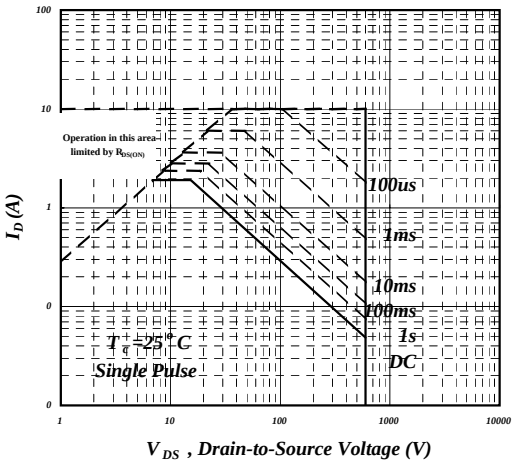


Fig 9. Maximum Safe Operating Area

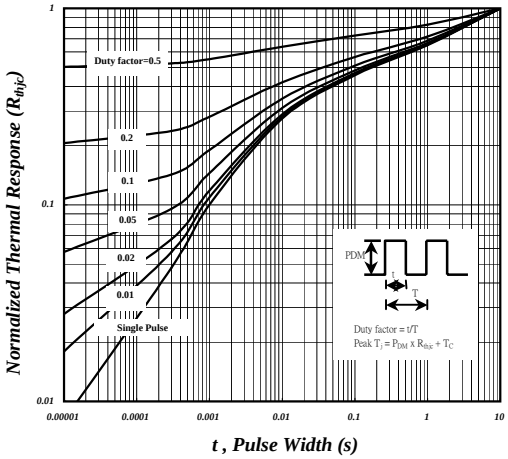


Fig 10. Effective Transient Thermal Impedance

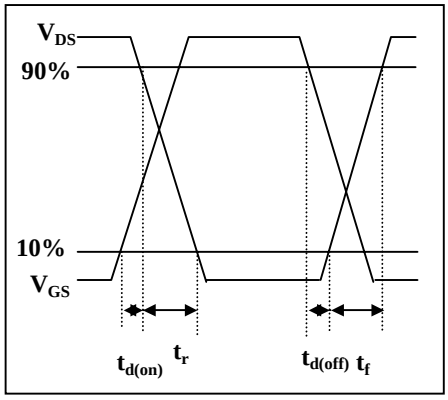


Fig 11. Switching Time Waveform

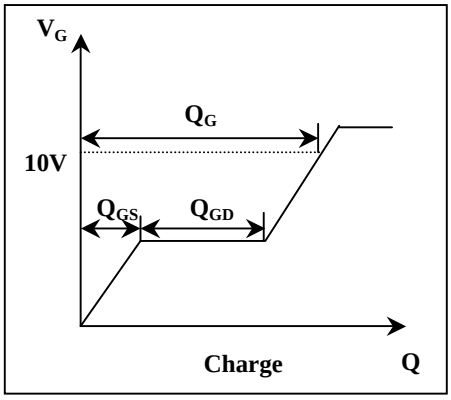


Fig 12. Gate Charge Waveform